

Notice of References Cited	Application/Control No. 10/050,179	Applicant(s)/Patent Under Reexamination LIN ET AL.	
	Examiner Magid Y Dimyan	Art Unit 2825	Page 1 of 1

U.S. PATENT DOCUMENTS

*	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
A	US-6,581,186	06-2003	Frost et al.	716/1
B	US-5,604,687	02-1997	Hwang et al.	703/12
C	US-5,713,666	02-1998	Seelin et al.	374/126
D	US-5,302,022	04-1994	Huang et al.	374/44
E	US-6,438,504	08-2002	Mikubo et al.	702/132
F	US-6,269,277	07-2001	Hershenson et al.	700/97
G	US-5,468,994	11-1995	Pendse, Rajendra D.	257/693
H	US-5,202,843	04-1993	Kunimine et al.	703/6
I	US-			
J	US-			
K	US-			
L	US-			
M	US-			

FOREIGN PATENT DOCUMENTS

*	Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
N					
O					
P					
Q					
R					
S					
T					

NON-PATENT DOCUMENTS

*	Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)		
U	Lasance, C.J.M., "Thermal Characterization of Electronic Parts with Compact Models: Interpretation, Application, and the Need for a Paradigm Shift" 13th Annual IEEE Semiconductor Thermal Measurement and Management Symposium, Jan. 28-30, 1997, pp. 40-48.		
V			
W			
X			

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.